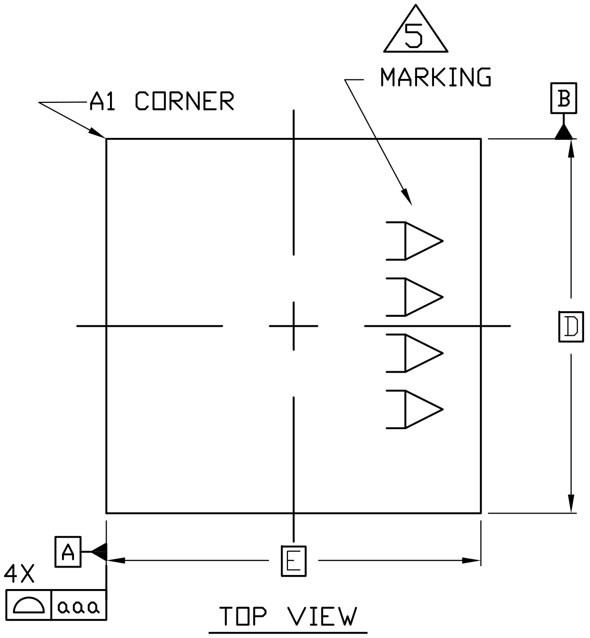
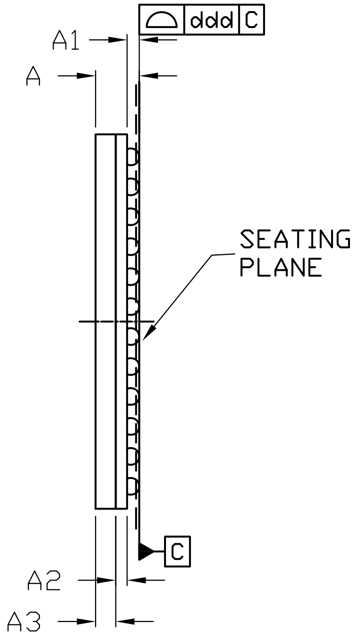
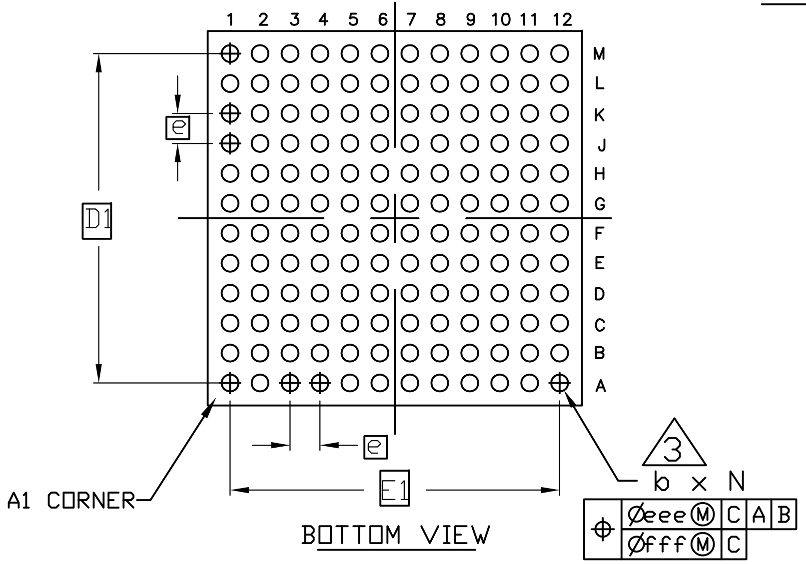


TOP VIEW



SIDE VIEW

DIMENSIONS			
REF.	MIN.	NOM.	MAX.
A	1.065	1.165	1.265
A1	0.250	–	0.400
A2	0.300 REF		
A3	0.540 REF		
D	10.000 BSC		
D1	8.800 BSC		
E	10.000 BSC		
E1	8.800 BSC		
b	0.400	–	0.500
e	0.800 BSC		
aaa	0.120		
ddd	0.150		
eee	0.150		
fff	0.080		
N	144		
PKG.	CODE: X14400F+2		



BOTTOM VIEW

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
3. 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM C.
4. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
6. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.
7. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.

-DRAWING NOT TO SCALE-

maxim
integrated™

TITLE:
PACKAGE OUTLINE, 144 BALLS
FLIP CHIP CSP, 10x10x1.165mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	
	21-100127	A	1/1